

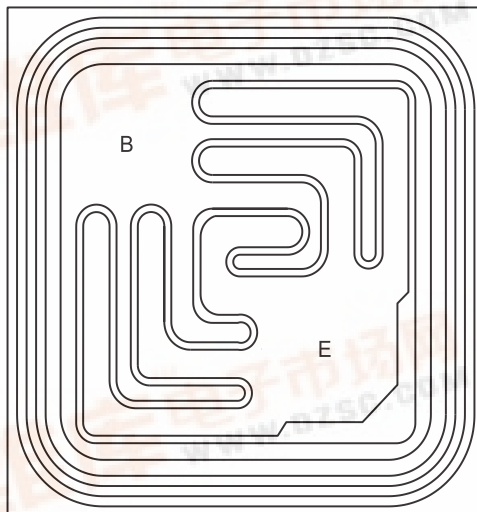
查询CP225供应商  
**PROCESS CP225**  
**Small Signal Transistor**  
NPN - Amp/Switch Transistor Chip

捷多邦，专业PCB打样工厂，24小时加急出货™  
**Central**  
**Semiconductor Corp.**

**PROCESS DETAILS**

|                          |                  |
|--------------------------|------------------|
| Process                  | EPITAXIAL PLANAR |
| Die Size                 | 19.8 x 19.8 MILS |
| Die Thickness            | 9.5 MILS         |
| Base Bonding Pad Area    | 4.3 x 4.3 MILS   |
| Emitter Bonding Pad Area | 4.3 x 4.3 MILS   |
| Top Side Metalization    | Al - 30,000Å     |
| Back Side Metalization   | Au - 12,000Å     |

**GEOMETRY**



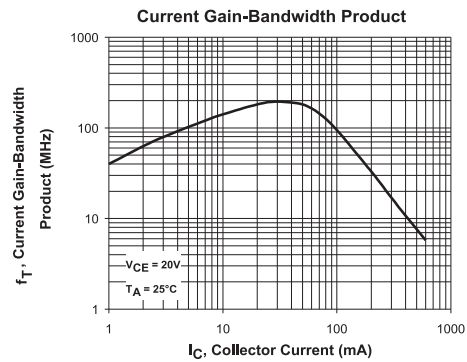
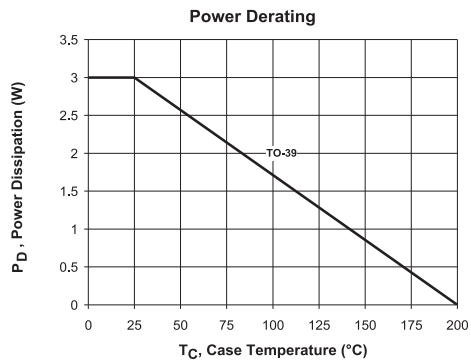
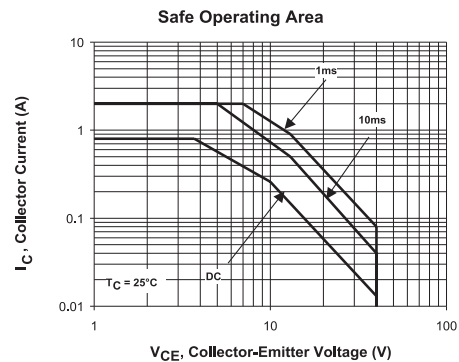
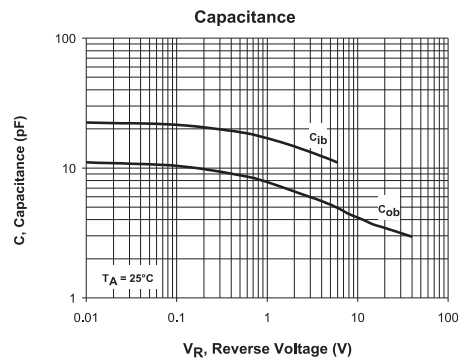
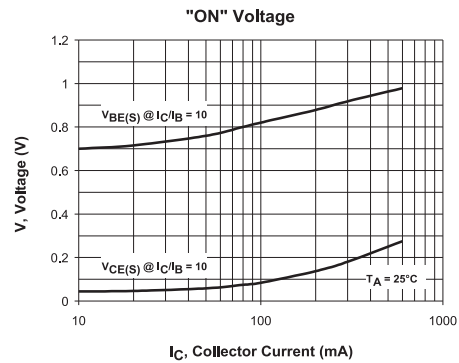
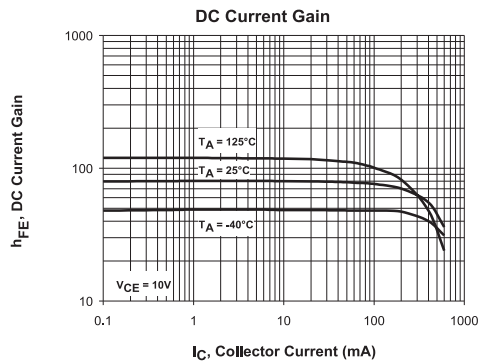
BACKSIDE COLLECTOR

**GROSS DIE PER 4 INCH WAFER**  
28,960

**PRINCIPAL DEVICE TYPES**  
2N2218A  
2N2221A

145 Adams Avenue  
Hauppauge, NY 11788 USA  
Tel: (631) 435-1110  
Fax: (631) 435-1824  
www.centrasemi.com

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